



**AAEON Technology INC.**  
ISO-9001/ISO-14001 Certified  
Industrial Automation PCs

# **SBC-659**

## **Thermal Image Analysis Report**

**Release Date: JAN.07, 2002**

---

**Issue Stamp**

---

**QA Manager**

---

**QE Manager**

---

**Test Engineer**

# Thermal Image Analysis

---

**I . Model Name: SBC-659 Rev.A1.0(BIOS 1.3 12/05/2001)**

**II . Description: AIO Half-size CPU Card. FC/Socket 370. 2 LAN.**

**III . Date: JAN. 07, 2002**

**IV . Measure Site: AAEON QE Dept.**

**V . Issued by : Linda Sun**

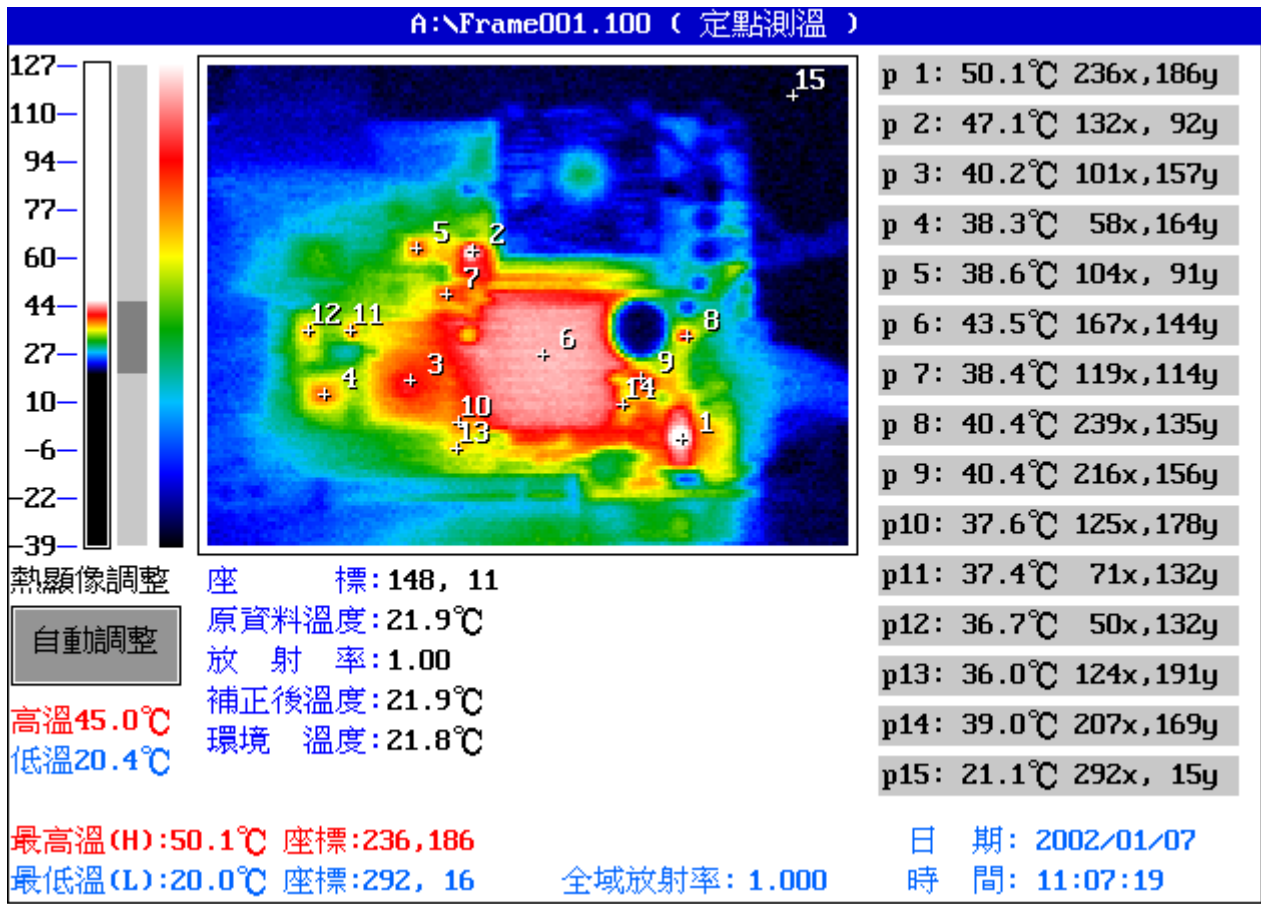
**VI.Equipment: TVS-100 series by NIPPON AVIONICS CO., LTD.**

**VII. Simulation Environment:**

- **Temperature: 21.1 degrees C**
- **CPU: Pentium III 550E MHz(100\*5.5)**
- **RAM: 64 MB SIEMENS HYB39S64160AT-8**
- **Hardware: Fujitsu MPC3043AP-E 4.3GB**
- **Application Software: 3D Mark2000**
- **Take Picture Time: Power on 30 minutes after**

# Temperature Profile Test:

Component Side:



Point	Position	Describe	Ts	Tm	Note
1	U15	ICS.94201DF		50.1°C	
2	Q1	REG.MOMC78L05ACPRP		47.1°C	
3	U12	INTEL.FW82801BA SL4HM		40.2°C	
4	U11	INTEL.GD82559		38.3°C	
5	U6	AVANCE LOGIC.ALC200		38.6°C	
6	U13	INTEL.FW82815 SL4DF		43.5°C	
7	TC14	POSCAP CAP. 330uF. 6.3V. 20%. D4.		38.4°C	
8	Q2	REG.UNISEM.US1010CY		40.4°C	
9	TC22	POSCAP CAP. 330uF. 6.3V. 20%. D4.		40.4°C	
10	Y4	X'TAL.EPSON.MC306(E-4-306-8)		37.6°C	
11	U8	REG.UNISEM.US1010CY		37.4°C	
12	U9	INTEL.DA82562ET		36.7°C	
13	U14	MAXIM.MAX706(SMD)		36.0°C	
14	TC28	MCC.4.7uF. 16V.		39.0°C	
15		The Room Temperature		21.1°C	

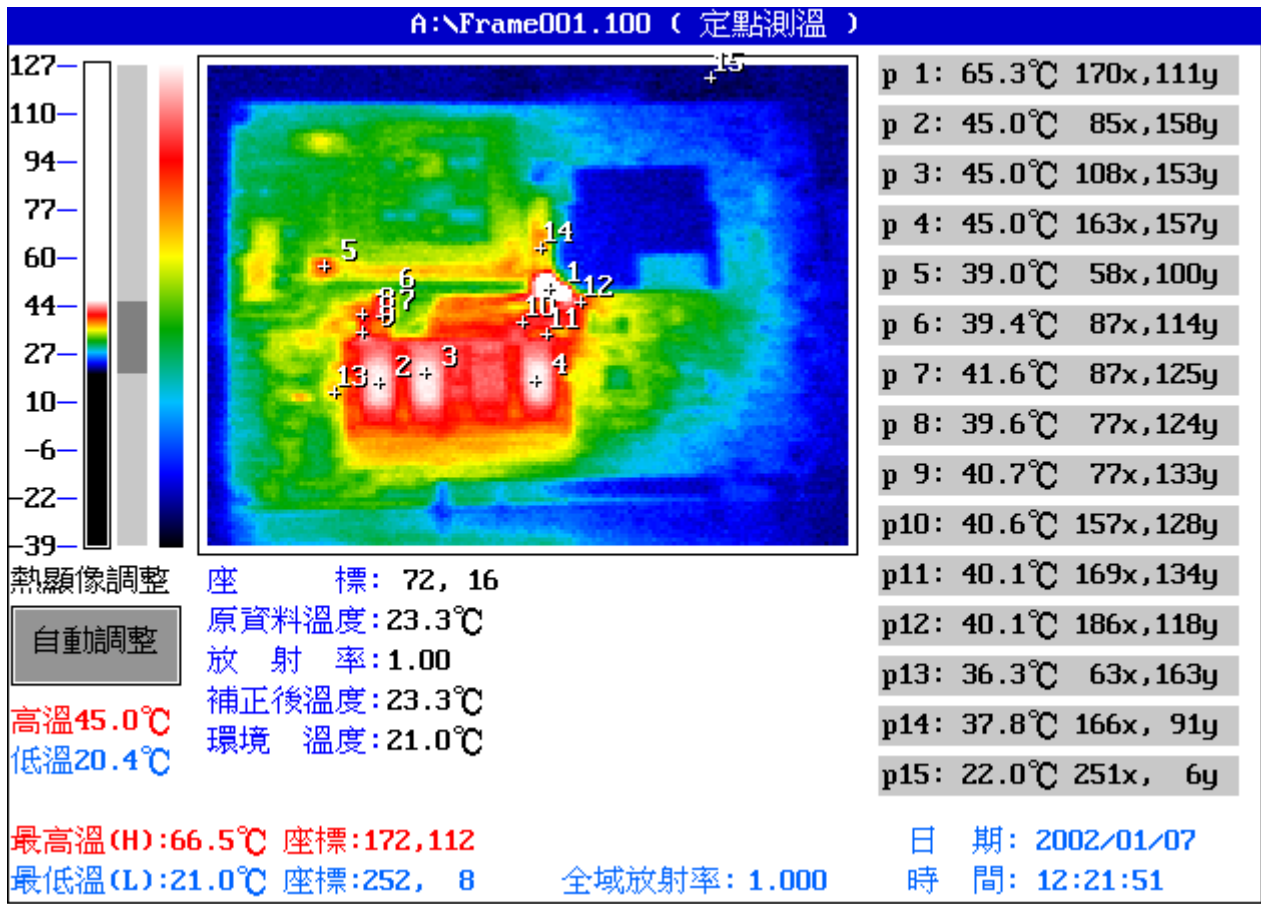
1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)

# Temperature Profile Test:

Component Side:



Point	Position	Describe	Ts	Tm	Note
1	Q8			65.3°C	
2	DIMM1	SIEMENS HYB39S64160AT-8		45.0°C	
3	DIMM1	SIEMENS HYB39S64160AT-8		45.0°C	
4	DIMM1	SIEMENS HYB39S64160AT-8		45.0°C	
5	Q10	PWR.SMD.TO-252AA N Channel		39.0°C	
6	D6	MOTOROLA.MBRS140T3		39.4°C	
7	D7	MOTOROLA.MBRS140T3		41.6°C	
8	U26	REG.UNISEM.US1010CY		39.6°C	
9	U29	REG.UNISEM.US1010CY		40.7°C	
10	TC53	SP CAP. 33uF. 6.3V. 20%. D.		40.6°C	
11	TC54	SP CAP. 33uF. 6.3V. 20%. D.		40.1°C	
12	Q9	PWR.SMD.TO-252AA N Channel		40.1°C	
13	TC59	POSCAP CAP. 100uF. 10V. 20%. D3.		36.3°C	
14		Open space		37.8°C	
15		The Room Temperature		22.0°C	

1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)